

60V N-Channel Enhancement Mode MOSFET

Description

The AP50N06Y uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS}=60V$ $I_D=50A$

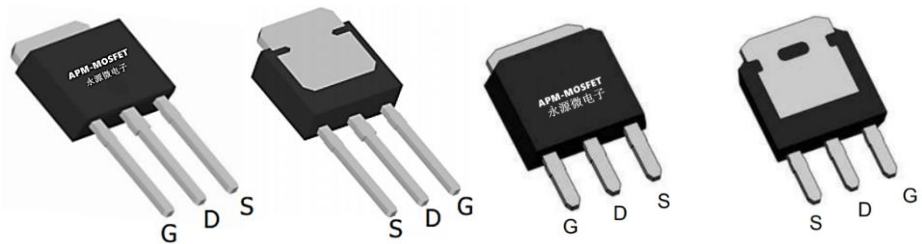
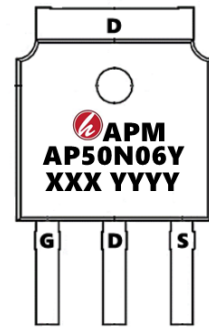
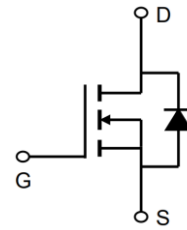
$R_{DS(ON)} < 20m\Omega$ @ $V_{GS}=10V$ (Type: 14m Ω)

Application

Battery protection

Load switch

Uninterruptible power supply



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
AP50N06Y	TO-251L-3L	AP50N06Y XXXX YYYY	4000
AP50N06Y	TO-251S-3L	AP50N06Y XXXX YYYY	4000

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	60	V
VGS	Gate-Source Voltage	± 20	V
$I_D@T_C=25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	50	A
$I_D@T_C=100^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	25	A
IDM	Pulsed Drain Current ²	90	A
EAS	Single Pulse Avalanche Energy ³	39.2	mJ
IAS	Avalanche Current	28	A
$P_D@T_C=25^\circ\text{C}$	Total Power Dissipation ⁴	45	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ⁴	2	W
TSTG	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	62	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	2.8	$^\circ\text{C/W}$

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Electrical Characteristics (T_J=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	60	65	---	V
ΔBVDSS/ΔT _J	BV _{DSS} Temperature Coefficient	Reference to 25°C, I _D =1mA	---	0.057	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	---	14	20	mΩ
		V _{GS} =4.5V, I _D =10A	---	18	25	
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	1.8	2.5	V
ΔVGS(th)	V _{GS(th)} Temperature Coefficient		---	-5.68	---	mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =48V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =48V, V _{GS} =0V, T _J =55°C	---	---	5	
IGSS	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
gfs	Forward Transconductance	V _{DS} =5V, I _D =15A	---	45	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.7	---	Ω
Q _g	Total Gate Charge (4.5V)	V _{DS} =48V, V _{GS} =4.5V, I _D =15A	---	19.3	---	nC
Q _{gs}	Gate-Source Charge		---	7.1	---	
Q _{gd}	Gate-Drain Charge		---	7.6	---	
Td(on)	Turn-On Delay Time	V _{DD} =30V, V _{GS} =10V, R _G =3.3Ω, I _D =15A	---	7.2	---	ns
T _r	Rise Time		---	50	---	
Td(off)	Turn-Off Delay Time		---	36.4	---	
T _f	Fall Time		---	7.6	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	2423	---	pF
C _{oss}	Output Capacitance		---	145	---	
C _{rss}	Reverse Transfer Capacitance		---	97	---	
I _s	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	35	A
ISM	Pulsed Source Current ^{2,5}		---	---	80	A
VSD	Diode Forward Voltage ²	V _{GS} =0V, I _s =A, T _J =25°C	---	---	1	V
t _{rr}	Reverse Recovery Time	IF=15A, dI/dt=100A/μs, T _J =25°C	---	16.3	---	nS
Q _{rr}	Reverse Recovery Charge		---	11	---	nC

Note :

- 1、he data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2、he data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3、he EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
- 4、he power dissipation is limited by 150°C junction temperature
- 5、he data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation

Typical Characteristics

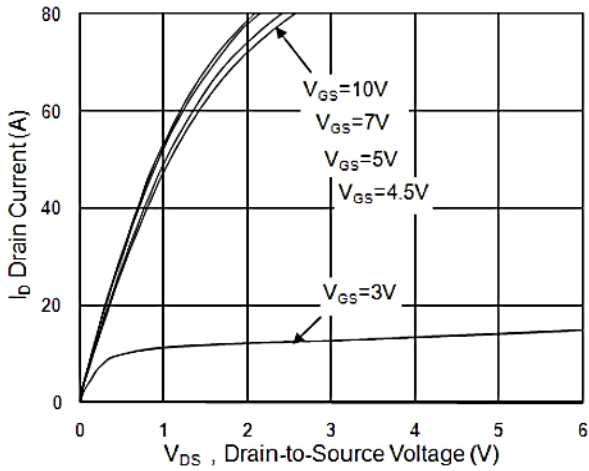


Fig.1 Typical Output Characteristics

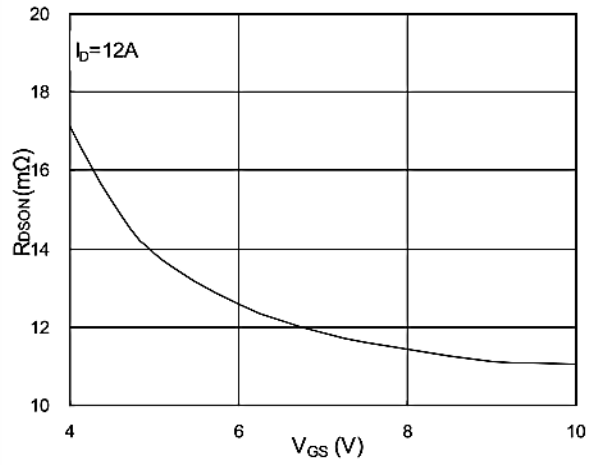


Fig.2 On-Resistance v.s Gate-Source

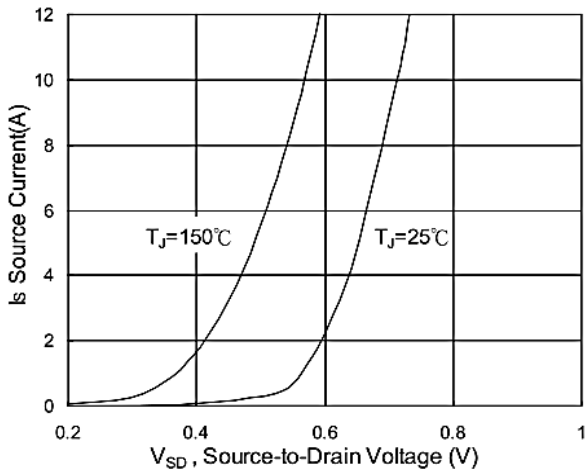


Fig.3 Forward Characteristics of Reverse

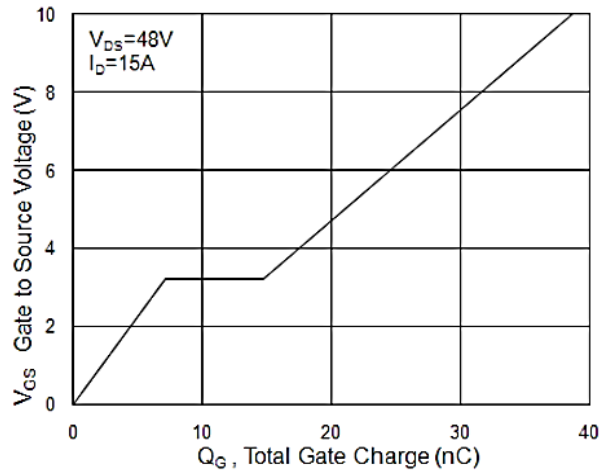


Fig.4 Gate-Charge Characteristics

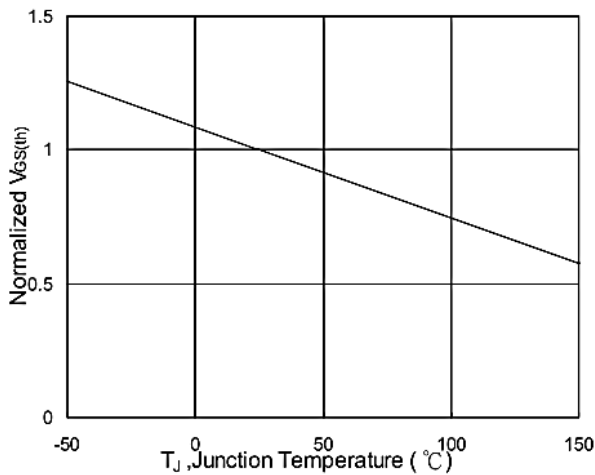


Fig.5 Normalized V_{GS} v.s T_J

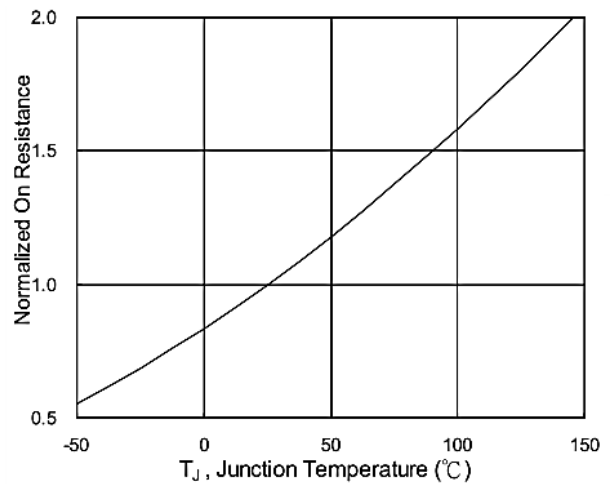


Fig.6 Normalized $R_{DS(on)}$ v.s T_J

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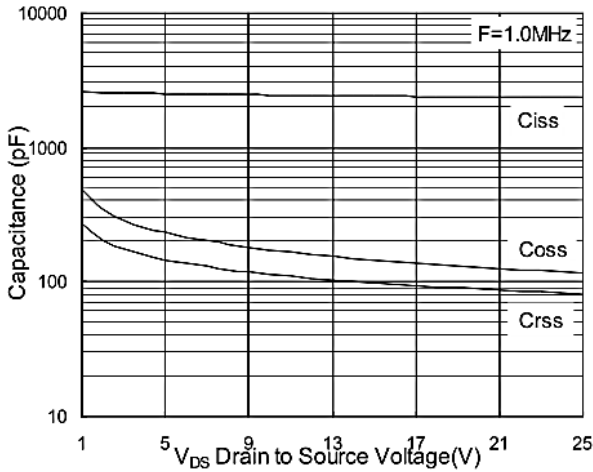


Fig.7 Capacitance

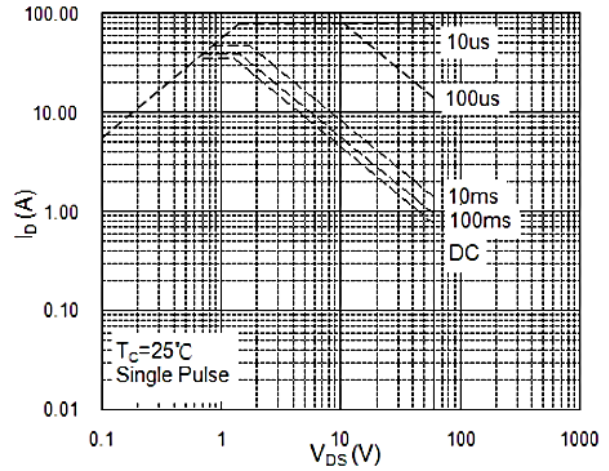


Fig.8 Safe Operating Area

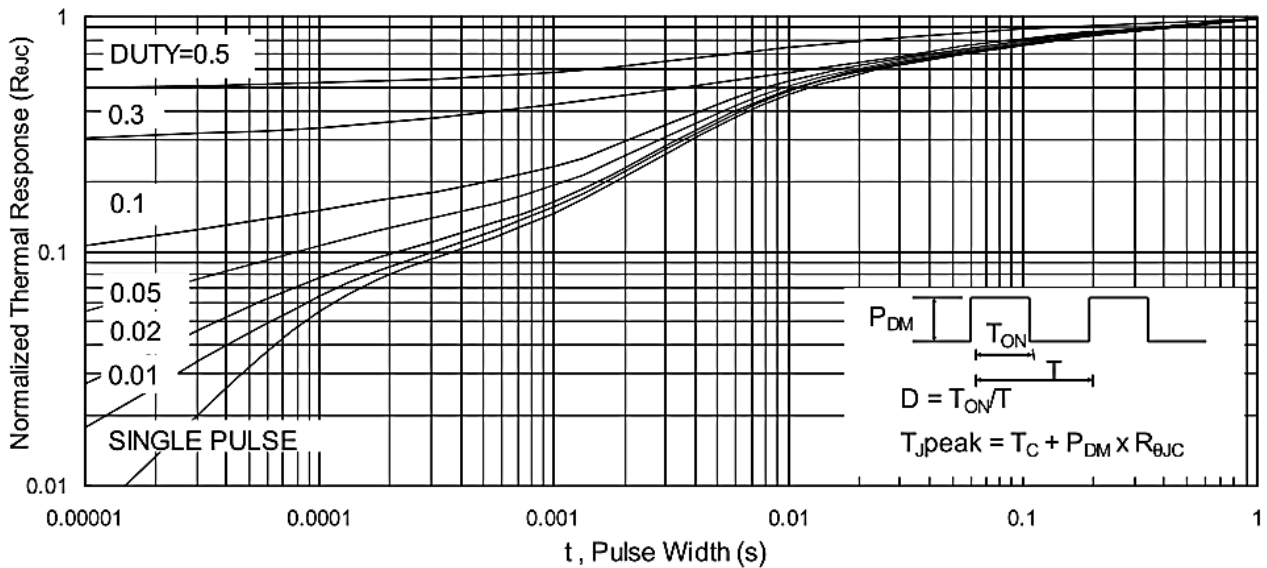


Fig.9 Normalized Maximum Transient Thermal Impedance

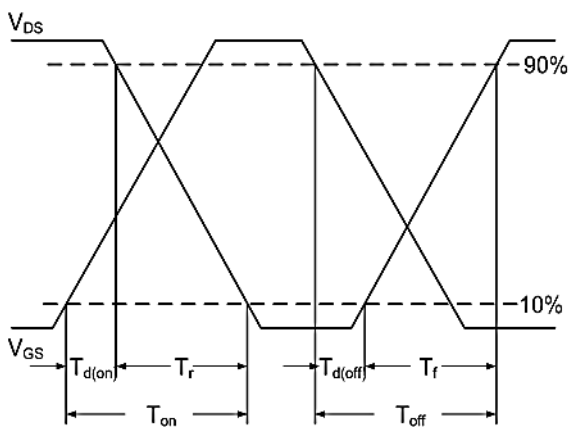


Fig.10 Switching Time Waveform

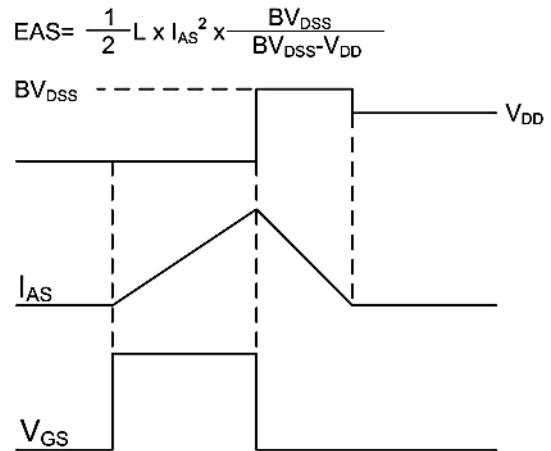
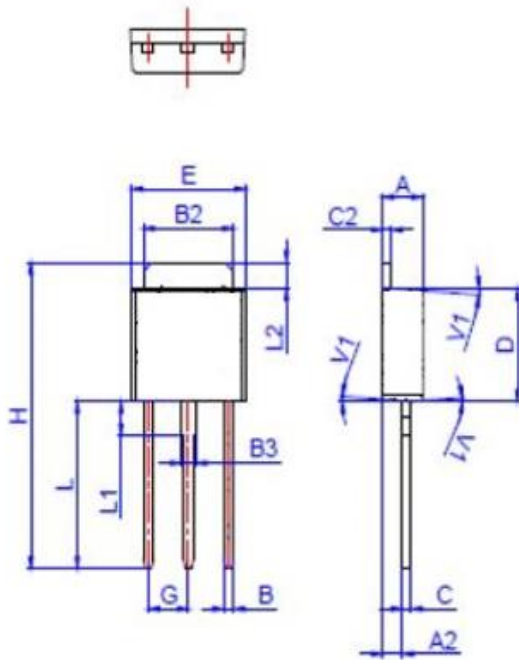


Fig.11 Unclamped Inductive Switching Waveform

Package Mechanical Data-TO-251L-3L



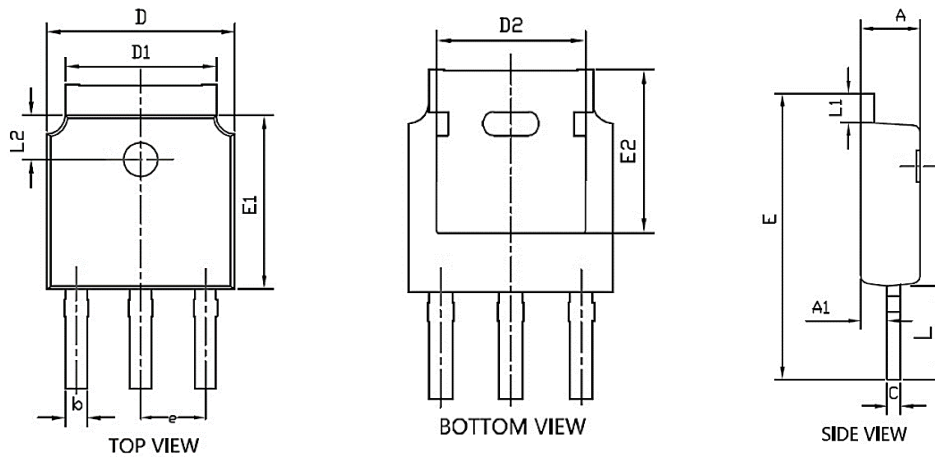
TO-251

Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.20		2.40	0.086		0.095
A2	0.90		1.20	0.035		0.047
B	0.55		0.65	0.022		0.026
B2	5.10		5.40	0.200		0.213
B3	0.76		0.85	0.030		0.033
C	0.45		0.62	0.018		0.024
C2	0.48		0.62	0.019		0.024
D	6.00		6.20	0.236		0.244
E	6.40		6.70	0.252		0.264
G		2.30			0.091	
H	16.0		17.0	0.630		0.669
L	8.90		9.40	0.350		0.370
L1	1.80		1.90	0.071		0.075
L2	1.37		1.50	0.054		0.059
V1		4°			4°	

Package Information -TO-251

OUTLINE	TUBE (PCS)	INNER BOX (PCS)	PER CARTON (PCS)
TUBE	80	4,000	32,000

Package Mechanical Data-TO-251S-3L



Symbol	Common		
	mm		
	Mim	Nom	Max
A	2.2	2.3	2.4
A1	0.9	1.0	1.1
b	0.66	0.76	0.86
C	0.46	0.52	0.58
D	6.50	6.6	6.7
D1	5.15	5.3	5.45
D2	4.6	4.8	4.95
E	10.4	----	11.5
E1	6.0	6.1	6.2
E2	5.400REF		
e	2.286BSC		
L	3.5	4.0	4.3
L1	0.9	---	1.27
L2	1.4	---	1.9

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AP50N06Y

60V N-Channel Enhancement Mode MOSFET

Edition	Date	Change
Rve1.0	2020/1/31	Initial release
Rve1.1	2021/8/35	New profile

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